

PCN N° 2024-168-A

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Dear	customer.	

please find attached our Infineon Technologies AG PCN:

Introduction of new final test and assembly site, changes in packing and assembly process affecting dedicated Traveo products

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before 2025-01-19.
- Infineon aligns with the widely-recognized JEDEC STANDARD "JESD46", which stipulates:
 "Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."
 Notwithstanding the aforesaid individual agreements shall prevail.

Your prompt reply will help Infineon to assure a smooth and well-executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.



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Products affected Please refer to attached affected product list PCN_2024-168-A_[customer-no].pdf

Detailed change information

Subject: Introduction of new final test and assembly site, changes in packing and assembly

process affecting dedicated Traveo products

Reason/Motivation: Capacity expansion of BE assembly to Advanced Semiconductor Engineering, Inc.,

Kaohsiung, Taiwan (ASE) to assure continuity of supply and enable flexible

Description	Old	New
PROCESS - ASSEMBLY:	EN-4600B (ATJ)	EN-4600B (ATJ)
Die attach material		AND
		EN-4900F (ASE)
PROCESS - ASSEMBLY:	(CYT2B6/7/9/L family) EME-G660B (ATJ)	(CYT2B6/7/9/L family) EME-G660B (ATJ)
Change of mold compound / encapsulation material	(CYT3BB/4BB family) EME-G660V (ATJ)	(CYT3BB/4BB family) EME-G660V (ATJ)
		AND
		EME-G631H (ASE)
PROCESS - ASSEMBLY:	ATJ:	ATJ:
Change of product marking	Country of origin JPN	Country of origin JPN
	Pin 1 identifier	Pin 1 identifier
	Ejector mark	Ejector mark
		AND
		ASE:
		Country of origin TWN
		Pin 1 identifier
		Ejector mark



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PROCESS - ASSEMBLY: Move all or parts of production to a different assembly site	Amkor Technology Japan, Inc., Fukuoka / Usuki, Japan (ATJ)	Amkor Technology Japan, Inc., Fukuoka / Usuki, Japan (ATJ) AND Advanced Semiconductor Engineering, Inc., Kaohsiung, Taiwan (ASE)
PACKING/SHIPPING: Change of carrier (tray, reel)	ATJ packing/tray/tape and reel	ATJ packing/tray/tape and reel AND ASE packing/tray/tape and reel AND BKK packing/tray/tape and reel
TEST FLOW: Move of all or part of electrical wafer test and/or final test to a different test site		Amkor Technology Japan, Inc., Fukuoka, Japan (ATJ) AND Advanced Semiconductor Engineering, Inc., Kaohsiung, Taiwan (ASE) AND Infineon Technologies (Thailand) Limited., Nonthaburi, Thailand Infineon Technologies Manufacturing (Thailand), Samut Prakan, Thailand (BKK)

Product identificationTraceability assured via date code and lot number.
No change in SP ordering number

Anticipated impact of changeBased on the qualification performed, Infineon does not expect any negative impact on quality, function and reliability.

DeQuMa-ID(s): SEM-PA-07 / SEM-PA-11 / SEM-PA-13 / SEM-PA-18 / SEM-PS-03 / SEM-TF-01



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Attachments PCN 2024-168-A [customer-no].pdf affected product list

Time schedule

Final qualification report	available
First samples available	on request
Intended start of delivery [1]	2025-06-09
Last order date (LOD) [2]	2025-06-09
Last delivery date (LDD) [3]	2026-06-09

^[1] Provided date or earlier after customer approval.

If you have any questions, please do not hesitate to contact your local sales office.

^[2] Last date where orders for unchanged products will be accepted.

^[3] Last date for delivery of unchanged products. Delivery of changed products can be earlier (see Intended start of delivery) and depends on approval.